

This listing of claims will replace all prior versions of claims in the present application:

**Listing of Claims:**

1. (currently amended) A method of making a lithography stage structure, said method comprising the following steps:
  - (a) providing a Ti doped SiO<sub>2</sub> glass powder comprised of a plurality of particles of Ti doped SiO<sub>2</sub> glass;
  - (b) providing a binder, said binder for binding said Ti doped SiO<sub>2</sub> glass particles together;
  - (c) depositing a layer of said Ti doped SiO<sub>2</sub> glass powder in a confined region to provide an underlying layer;
  - (d) applying said binder to one or more selected regions of said layer of Ti doped SiO<sub>2</sub> glass powder to bind at least two of said Ti doped SiO<sub>2</sub> glass particles together to form a primitive, said applying binder bonding said glass powder together at said one or more selected regions;
  - (e) depositing an above layer of said Ti doped SiO<sub>2</sub> glass powder above said deposited layer;
  - (f) applying said binder to one or more selected regions of said above layer with said binder bonding said glass powder together at said one or more selected regions;
  - (g) repeating steps (e) and (f) a selected number of times to produce a selected number of successive layers with said binder bonding said successive layers together;
  - (h) removing unbonded glass powder which is not at said one or more selected regions to provide a bonded Ti doped SiO<sub>2</sub> glass powder lithography stage structure.
2. (previously presented) A method as claimed in claim 1, further including sintering said bonded Ti doped SiO<sub>2</sub> glass lithography stage structure into a densified glass lithography stage structure.

3. (previously presented) A method as claimed in claim 2 wherein sintering into a densified glass lithography stage structure includes sintering at a temperature of at least 1100°C.
4. (previously presented) A method as claimed in claim 2 wherein sintering into a densified glass lithography stage structure includes hot isostatic pressing.
5. (previously presented) A method as claimed in claim 1, wherein applying said binder includes depositing said binder to form a skeletal network.
6. (previously presented) A method as claimed in claim 1, wherein applying said binder includes depositing said binder to form a lithography wafer receiver.
7. (previously presented) A method as claimed in claim 6 wherein depositing said binder to form a lithography wafer receiver includes forming a flat planar surface.
8. (previously presented) A method as claimed in claim 7 further including depositing said binder to form a skeletal network frame for said lithography wafer receiver.
9. (previously presented) A method as claimed in claim 1 wherein applying said binder includes depositing said binder to form a lithography mask receiver .
10. (previously presented) A method as claimed in claim 1 wherein applying said binder includes depositing said binder to form a mirror surface.
11. (currently amended) A method as claimed in claim 1 wherein said Ti doped SiO<sub>2</sub> glass powder contains 3 to 20 wt. % ~~TiO<sub>2</sub>~~ TiO<sub>2</sub>.
12. (previously presented) A method as claimed in claim 1, wherein providing a binder comprises providing a mixture of H<sub>2</sub>O and Ti doped SiO<sub>2</sub> glass soot.

13. (currently amended) A method as claimed in claim 12 wherein said mixture of  $H_2O$   $H_2O$  and Ti doped  $SiO_2$  glass soot includes ammonia.

14. (previously presented) A method as claimed in claim 1 wherein providing a Ti doped  $SiO_2$  glass powder includes providing a conglomerated Ti doped  $SiO_2$  glass powder comprised a plurality of cemented together primary glass particles .

15. (previously presented) A method as claimed in claim 14 wherein said primary glass particles are cemented together with an organic binder .

16. (previously presented) A method as claimed in claim 15 wherein providing a binder comprises providing a water binder, said water binder for reactivating said organic binder.

17. (previously presented) A method as claimed in claim 2 wherein sintering includes sintering in a vacuum.

18. (previously presented) A method as claimed in claim 5 wherein forming a skeletal network includes forming a web structure with a wall thickness  $\leq 3$  mm.

19. (previously presented) A method as claimed in claim 1, wherein applying said binder to selected regions includes projecting a plurality of binder droplets from a binder deposition head.

20. (previously presented) A method as claimed in claim 1 wherein applying said binder to selected regions includes ink jet print depositing said binder.

21. (currently amended) A method as claimed in claim 1 wherein depositing said Ti doped  $SiO_2$  glass powder includes depositing with a powder distribution head.

22. (previously presented) A method as claimed in claim 1 wherein said Ti doped  $SiO_2$  glass powder has an average particle size  $\geq 10$  microns.

23. (previously presented) A method as claimed in claim 1 wherein said Ti doped SiO<sub>2</sub> glass powder has an average particle size  $\geq 20$  microns.

24. (previously presented) A method as claimed in claim 19 further including providing relative motion between said binder deposition head and said deposited layer of glass powder.

25. (currently amended) A method of making a lithography stage structure, said method comprising the following steps:

- (a) providing a plurality of glass particles;
- (b) providing a binder, said binder for binding said glass particles together;
- (c) depositing a layer of said glass particles in a confined region to provide an underlying layer;
- (d) applying said binder to one or more selected regions of said layer of glass particles to bind at least two of said glass particles together to form a primitive, said applying binder bonding said glass particles together at said one or more selected regions;
- (e) depositing an above layer of said glass particles above said deposited layer;
- (f) applying said binder to one or more selected regions of said above layer with said binder bonding said glass particles together at said one or more selected regions;
- (g) repeating steps (e) and (f) a selected number of times to produce a selected number of successive layers with said binder bonding said successive layers together;

removing unbonded glass particles which are not at said one or more selected regions to provide a bonded glass particle lithography stage structure.

26. (previously presented) A method as claimed in claim 25, further including sintering said bonded glass particle lithography stage structure into a densified glass lithography stage structure.

27. (previously presented) A method as claimed in claim 26 wherein sintering into a densified glass lithography stage structure includes sintering at a temperature of at least 1100°C.

28. (previously presented) A method as claimed in claim 26 wherein sintering into a densified glass lithography stage structure includes hot isostatic pressing.

29. (previously presented) A method of making an EUV lithography structure, said method comprising the following steps:

- (a) providing a plurality of glass particles;
- (b) providing a binder, said binder for binding said glass particles together;
- (c) depositing a layer of said glass particles in a confined region to provide an underlying layer;
- (d) applying said binder to one or more selected regions of said layer of glass particles to bind at least two of said glass particles together to form a primitive, said applying binder bonding said glass particles together at said one or more selected regions;
- (e) depositing an above layer of said glass particles above said deposited layer;
- (f) applying said binder to one or more selected regions of said above layer with said binder bonding said glass particles together at said one or more selected regions;
- (g) repeating steps (e) and (f) a selected number of times to produce a selected number of successive layers with said binder bonding said successive layers together;
- (h) removing unbonded glass particles which are not at said one or more selected regions to provide a bonded glass particle EUV lithography structure.

30. (previously presented) A method as claimed in claim 29, further including sintering said bonded glass particle lithography structure into a densified EUV lithography structure.

31. (previously presented) A method as claimed in claim 30 wherein sintering into a densified EUV lithography structure includes sintering at a temperature of at least 1100°C.

32. (previously presented) A method as claimed in claim 30 wherein sintering into a densified EUV lithography structure includes hot isostatic pressing.